

TITLEPOLYIMIDE COMPOSITIONS HAVING RESISTANCE TO WATER  
SORPTION, AND METHODS RELATING THERETOABSTRACT

5           Water absorption resistant polyimide pastes (or solutions), are  
particularly useful to make electronic screen printable pastes and the  
electronic components made from these pastes. A group of soluble  
polyimides and their solvents were discovered to be particularly resistant  
to moisture absorption. These polyimide solutions optionally contain  
10 polyimides also containing cross-linkable monomers and/or thermal cross-  
linking agents. In addition, these polyimide pastes may optionally contain  
adhesion promoting agents, blocked isocyanates, metals, metal oxides,  
and other inorganic fillers. The polyimide pastes (or solutions) of the  
present invention have a polyimide with a glass transition temperature  
15 greater than 250 °C, have a water absorption factor of less than 2%, and a  
have a positive solubility measurement.

20

25

30

35

KK/dmm